



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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REV.	DATE	DCN NO.	DESCRIPTION	DR.	CHK.	APPD.	APPD.
8	25.May.2010	069988	Added New Items		K.ASHIBU	T.NEMOTO	A.NATORI
9	9.Sep.2010	070484	Changed Marking Position Of Lot Number		K.ASHIBU	T.NEMOTO	A.NATORI
10	27.Oct.2010	070937	Changed Applicable F.P.C. Dimension(REF.)		K.ASHIBU	T.NEMOTO	A.NATORI

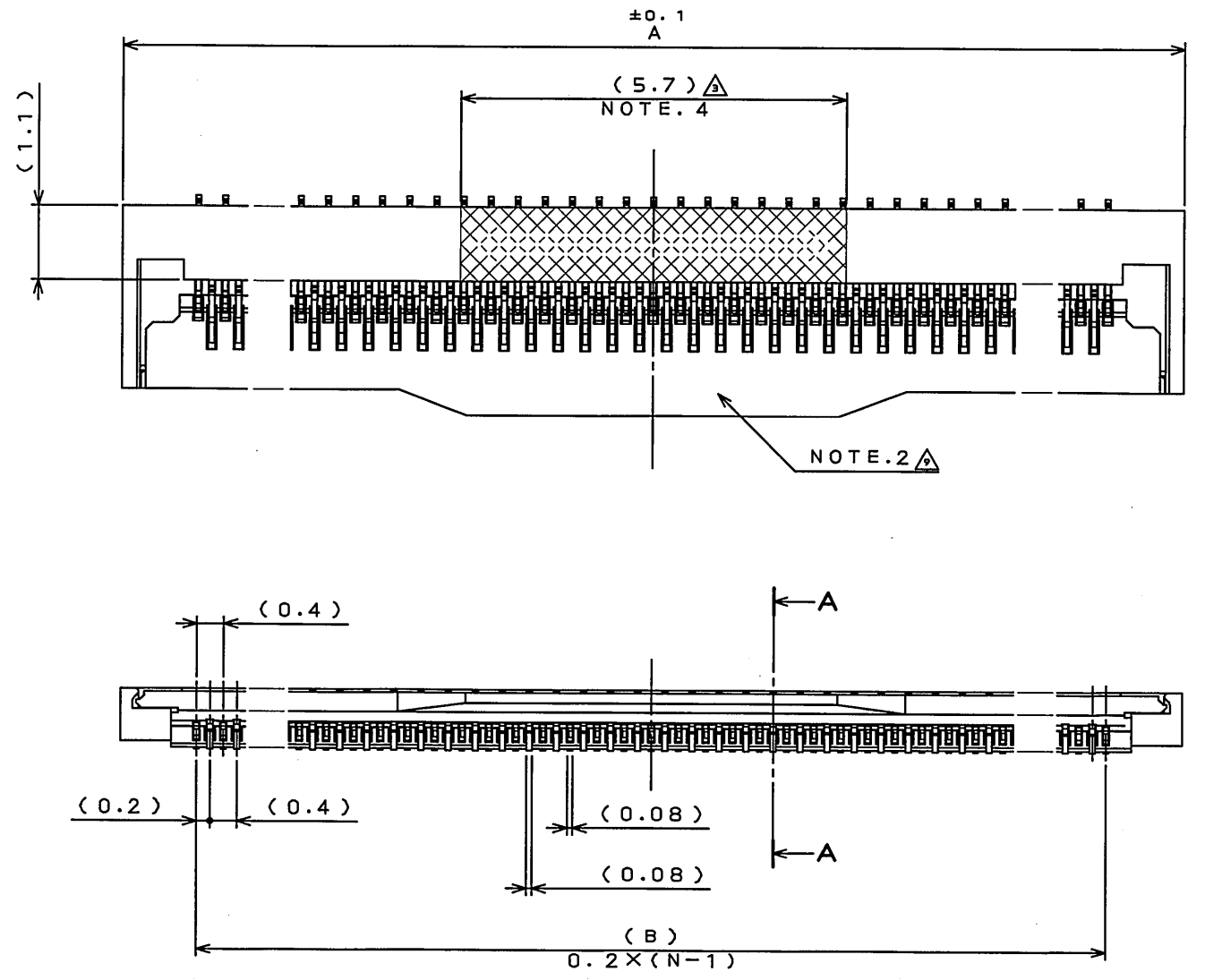
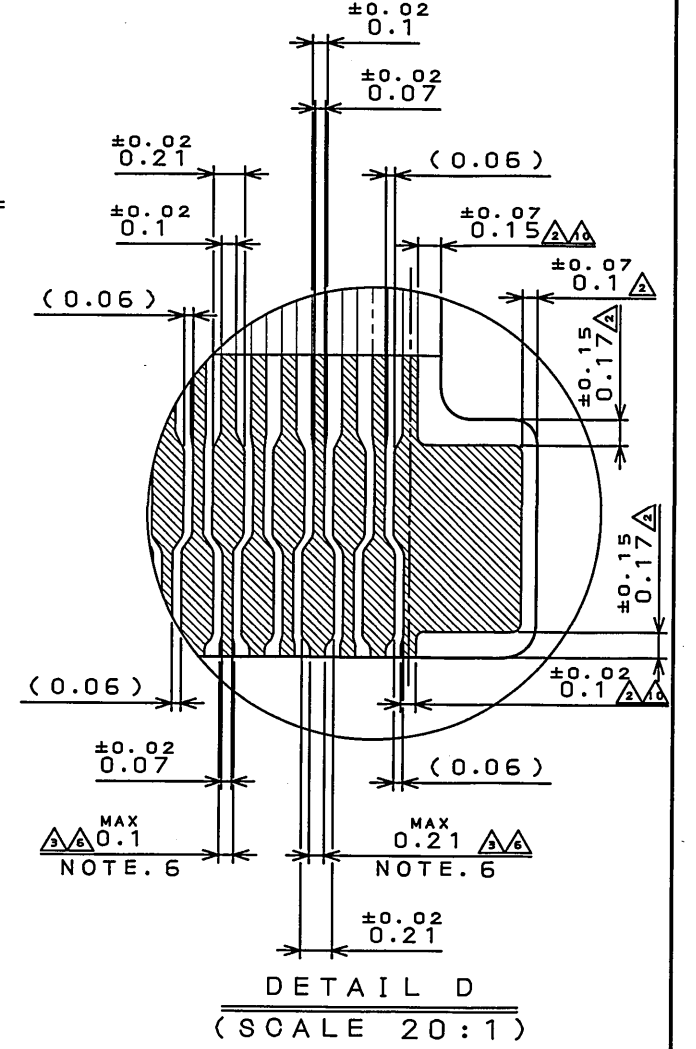
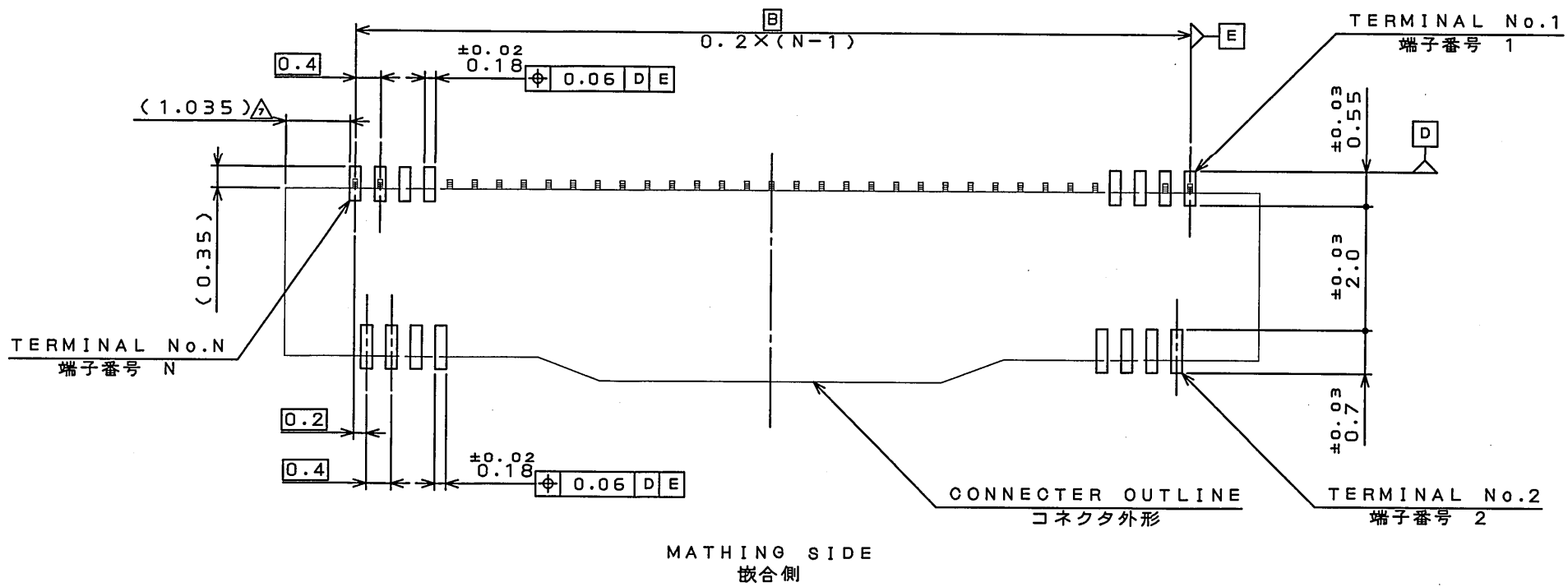
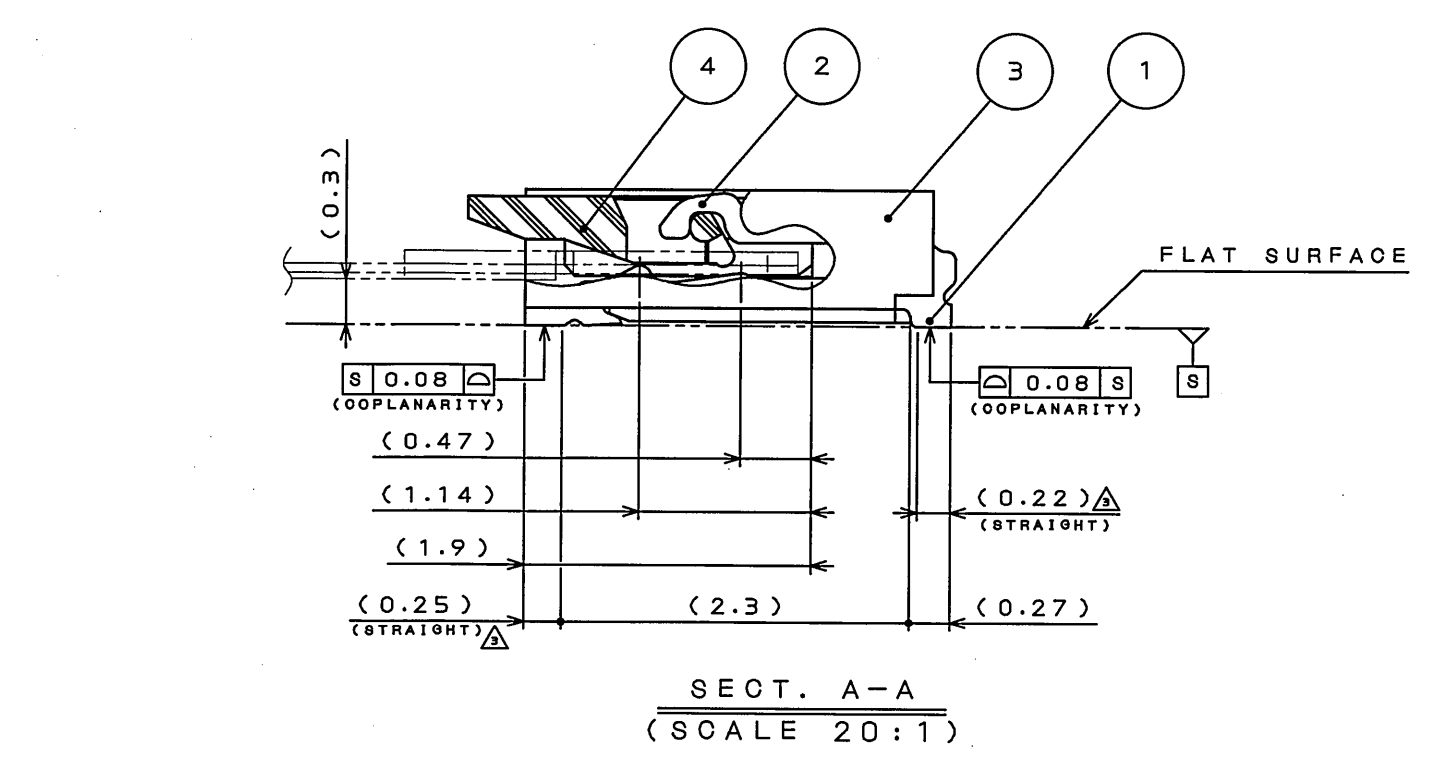
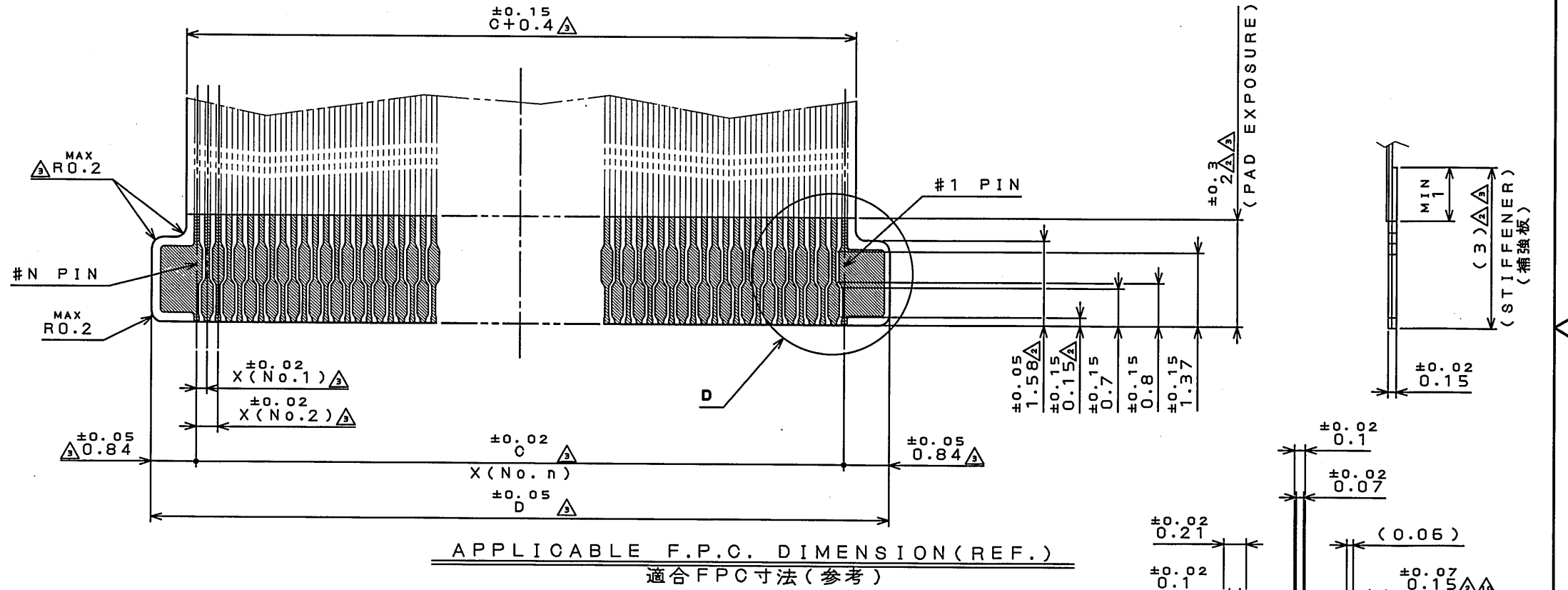
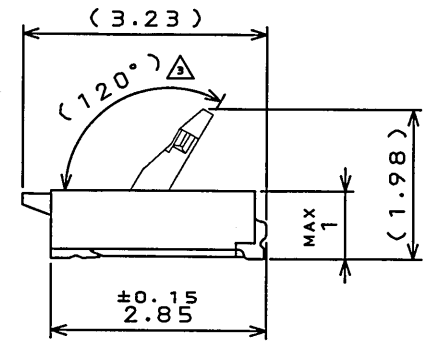


TABLE 3. DIMENSIONS

NO.	X
1	0.2
2	0.4
3	0.6
.	.
.	.
n	0.2 x (n-1)



APPLICABLE P.C.B. DIMENSION (REF.)
適合基板寸法 (参考)

NOTE
 1. REFER TO TABLE 2 FOR RECOMMENDED FPC COMPOSITION.
 2. LOT NUMBER IS MARKED ON THE TOP PORTION OF THE CONNECTOR.
 3. A NICKEL BARRIER EXISTS BETWEEN EACH CONTACT POINT AND TAIL.
 4. THE DIMENSIONS OF VACUUMING COVER AREA.
 5. OVERLAY EDGE INCLUDES A PROJECTION OF AN ADHESION LAYER.
 6. DIMENSION OF TIP IS OPTIONAL WITHIN ABOVE RANGE WITHOUT PATTERN PEELING.

TABLE 2. RECOMMENDED FPC COMPOSITION

COMPOSITION 層名	RECOMMENDED 推奨
GOLD PLATING 金めっき	ELECTROLYSIS PLATING 電解めっき
COPPER 銅箔	ROLLED MATERIAL 圧延銅
ADHESIVE 接着剤	THERMOSETTING ADHESIVE 熱硬化性
BASE FILM ベースフィルム	POLYIMIDE ポリイミド
ADHESIVE 接着剤	THERMOSETTING ADHESIVE 熱硬化性
REINFORCE PLATE 補強板	POLYIMIDE ポリイミド

TABLE 1. DIMENSIONS

PRODUCT NO.	A	B	C	D
FF0825SA1	7.05	4.80	4.80	6.48
FF0829SA1	7.85	5.60	5.60	7.28
FF0841SA1	10.25	8.00	8.00	9.68
FF0851SA1	12.25	10.00	10.00	11.68
FF0871SA1	16.25	14.00	14.00	15.68
FF0881SA1	18.25	16.00	16.00	17.68

NO.	DESCRIPTION	QTY.	MATERIAL	FINISH	REMARKS
4	ACTUATOR アクチュエータ	1	HEAT RESISTING PLASTIC 耐熱プラスチック		COLOR: BLACK / 色相: 黒色 UL94V-0
3	BASE INSULATOR ベースインシュレータ	1	HEAT RESISTING PLASTIC 耐熱プラスチック		COLOR: BEIGE / 色相: 肌色 UL94V-0
2	CONTACT 2 コンタクト 2	(N-1) 2	COPPER ALLOY 銅合金		PARTIAL GOLD (0.1μm MIN) OVER NICKEL ニッケル上部分 Au 0.1μm 以上
1	CONTACT 1 コンタクト 1	(N+1) 2	COPPER ALLOY 銅合金		PARTIAL GOLD (0.1μm MIN) OVER NICKEL ニッケル上部分 Au 0.1μm 以上

DOF-0-213E(05.08)

SIZE A2